

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): [[A]] An electronic parts packaging structure comprising:
a wiring substrate [[in]] which has a bump of an electronic parts is bonded to a connection
pad of the wiring substrate, which has a structure in which a wiring pattern including the connection
pad is provided on an insulating film, by an ultrasonic flip-chip packaging, wherein a via hole into
which a via post acting as a strut to support the connection pad upon the ultrasonic flip-chip
packaging is filled is arranged in the insulating film under the connection pad structure in which a
wiring pattern including a connection pad to which a bump of an electronic parts is bonded is
provided on an insulating film, and the wiring substrate in which a via hole into which a via post is
filled is arranged in a portion in the insulating film under the connection pad; and
the electronic parts whose bump is ultrasonic flip-chip packaged to the connection pad;
wherein said via posts in said via holes are positioned at positions corresponding to said
bumps of said electronic parts respectively, so that said via ports function as struts which can prevent
that said connection pads eat into the insulating film by withstanding pressure or ultrasonic vibration,
in case that electronic parts whose pumps are ultrasonic flip-chip packaged to said connection pads.

Claim 2 (Currently Amended): [[A]] An electronic parts packaging structure comprising:
a wiring substrate [[in]] which has a structure in which a wiring pattern including a
connection pad to which a bump of an electronic parts is bonded is provided on an insulating film,
and the wiring substrate in which a via hole into which a via post is filled is arranged in a
predetermined portion in the insulating film under the wiring pattern connected connection pad
within 200 μ m from the connection pad; and

~~bump of an the electronic parts is bonded to a connection pad of the wiring substrate, which~~
~~has a structure in which a wiring pattern including the connection pad is provided on an insulating~~
~~film, by an ultrasonic flip-chip packaging, wherein a via hole into which a via post acting as a strut~~
~~to support whose bump is ultrasonic flip-chip packaged to the connection pad upon the ultrasonic~~
~~flip-chip packaging is filled is arranged in a predetermined portion of the insulating film under the~~
~~wiring pattern connected to the connection pad within 200 μ m from the connection pad,~~

wherein said via posts in said via holes are positioned at positions within 200 μ m from said
connection pad concerning with said bumps of said electronic parts respectively, so that said via
posts function as struts which can prevent that said connection pads eat into the insulating film by
withstanding pressure or ultrasonic vibration, in case that electronic parts whose bumps are
ultrasonic flip-chip packaged to the connection pad.

Claim 3 (Currently Amended): ~~A wiring substrate~~ The electronic parts packaging structure according to claim 1 or 2, wherein the via hole is a dummy via hole and a normal via hole is arranged separately under a predetermined portion of the wiring pattern connected to the connection pad.

Claim 4 (Currently Amended): ~~A wiring substrate~~ The electronic parts packaging structure according to claim 1 or 2, wherein the wiring substrate has a plurality of connection pads, a plurality of via holes associated with said plurality of connection pads are arranged in a state that a dummy via hole and normal via holes are arranged mixedly, and a normal via hole is arranged separately under a predetermined portion of the wiring pattern connected to the connection pad, in the wiring pattern in which the dummy via hole is arranged under the connection pad or the wiring pattern.

Claim 5 (Currently Amended): ~~A wiring substrate~~ The electronic parts packaging structure according to claim 3, wherein the normal via hole is arranged in a position that is away from the connection pad in excess of 200 μm .

Claim 6 (Withdrawn): A wiring substrate according to claim 3, wherein a via post filled in the dummy via hole is formed between an upper surface of the via post and a lower surface of the connection pad or the wiring pattern via the insulating film.

Claim 7 (Withdrawn): A wiring substrate according to claim 1 or 2, wherein the wiring substrate has a plurality of connection pads corresponding to a plurality of bumps of the electronic parts, and a plurality of via holes associated with the plurality of connection pads, and a diameter of the via holes formed in portions corresponding to both end portions of the electronic parts is set larger than a diameter of the via hole formed in a portion corresponding to a center portion of the electronic parts, in an oscillation direction of an ultrasonic wave applied when the electronic parts is packaged onto the wiring substrate by the ultrasonic flip-chip packaging.

Claim 8 (Currently Amended): ~~A wiring substrate~~ The electronic parts packaging structure according to claim 1 or 2, wherein the insulating film on the wiring substrate is made of resin.

Claim 9 (Canceled).

Claim 10 (Currently Amened): An electronic parts packaging structure according to claim [[9]] 1, wherein the bump of the electronic parts is made of gold, and at least a surface layer portion of the connection pad of the wiring substrate is made of gold.